# **Specification of Thermoelectric Module**

# TEFC2-59-31-02

## Description

The TEFC2-59-31-02 is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 180  $^{\circ}$ C applications. It is a 59-31 couples module in size of 12 mm × 12 mm (top) / 15 mm × 18 mm (bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

### Features

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

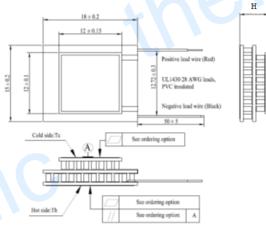
### Application

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

### **Performance Specification Sheet**

Th ( °C)	27	50	Hot side temperature at environment: dry air, N2
DT <sub>max</sub> (°C)	94	105	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	6.9	7.6	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (Amps)	1.7	1.7	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	4.4	4.9	Cooling capacity at cold side of the module under $DT = 0$ °C
AC resistance (Ohms)	4.8	5.2	The module resistance is tested under AC
Tolerance (%)	±5		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



# **Ordering Option**

				ΙТ		
Suffix	Thickness	Flatness/	Lead wire length(mm)			
	(mm)	Parallelism (mm)	Standard/Optional length			
TF	0: 6.1 ±0.40	0: 0.050/0.050	50 ±5/Specify			
TF	1:6.1 ±0.30	1: 0.030/0.030	50 ±5/Specify	T		
TF	2: 6.1 ±0.15	2: 0.015/0.015	50 ±5/Specify	T		
Eg. TF01: Thickness 6.1 ±0.40 (mm) and Flatness/ Parallelism 0.030/0.030						

## **Manufacturing Options**

# 1. T100: BiSn (Tmelt=138 °C)

- 2. T200: CuSn (Tmelt = 227 °C)
- 2. 1200. Cush (Thet = 227 C

### B. Sealant:

A. Solder:

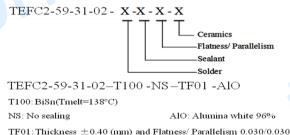
- 1. NS: No sealing (Standard)
- 2. SS: Silicone sealant
- 3. EPS: Epoxy sealant
- 4. Customer specify sealing

- C. Ceramics:
- 1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
- 2. Aluminum Nitride (AlN)

#### **D.** Ceramics Surface Options:

- 1. Blank ceramics (not metallized)
- 2. Metallized (Au plating)

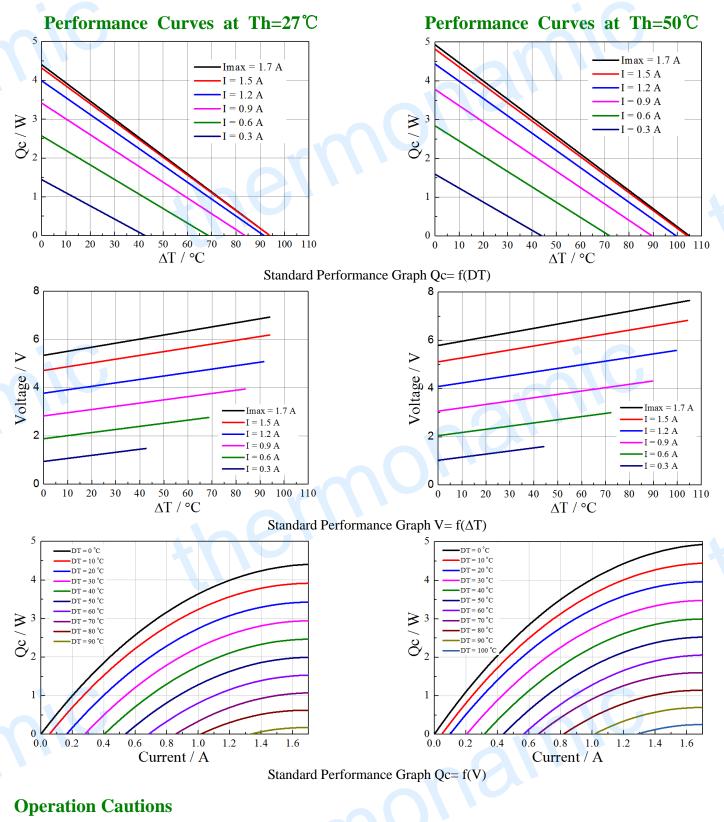
## Naming for the Module



Creative technology with fine manufacturing processes provides you the reliable and quality products Tel: +86-791-88198288 Fax: +86-791-88198308 Email: <u>sales@thermonamic.com.cn</u> Web Site: www.thermonamic.com.cn

# **Specification of Thermoelectric Module**

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- Cold side of the module sticked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation or storage module below 100  $\mathbb{C}$

- $\bullet$  Operation below  $I_{max} \text{ or } V_{max}$
- Work under DC